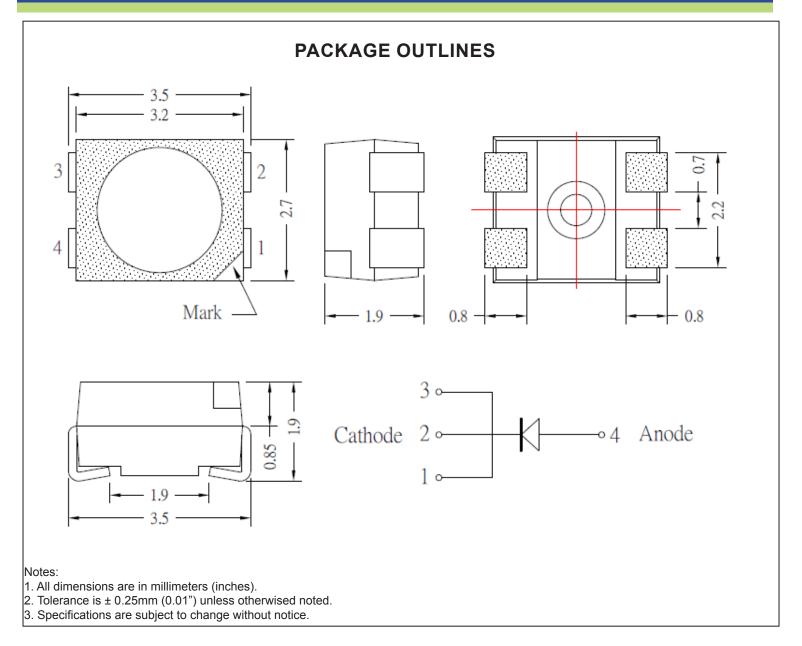


SPECIFICATION





Part Number	Chip Material	Color of Emission	Color of Emission Lens Type	
CSP1311R3C-4	InGaAIP	Red	Water Clear	120°





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	70	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	150	mW	
Operating Temperature Range	Тор	-30~+100	°C	
Storage Temperature Range	Тѕтс	-40~+100	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lfp	100	mA	
Soldering Temperature	TSOL	Max 265°C for 10 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Deremeter	Symbol	Test Condition	Value			Linit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	١v	IF = 50mA	1500	2200	-	mcd
Forward Voltage	Vf	IF = 50mA	-	2.4	3.0	V
Reverse Leakage Current	lr	VR = 5V	-	-	10	μA
Viewing Angle at 50% Iv	201/2	IF = 50mA	-	120	-	Deg
Peak Wavelength	λp	IF = 50mA	-	635	-	nm
Dominant Wavelength	λD	IF = 50mA	615	625	635	nm

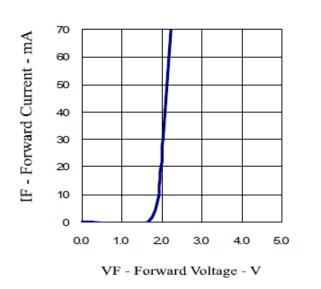
*Tolerance of viewing angle: -10 / +5 deg.

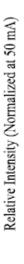




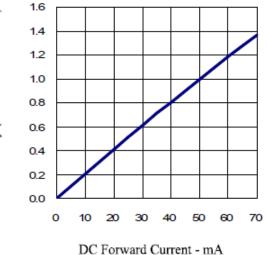
OPTICAL CHARACTERISTIC CURVES

Forward Current vs. Forward Voltage



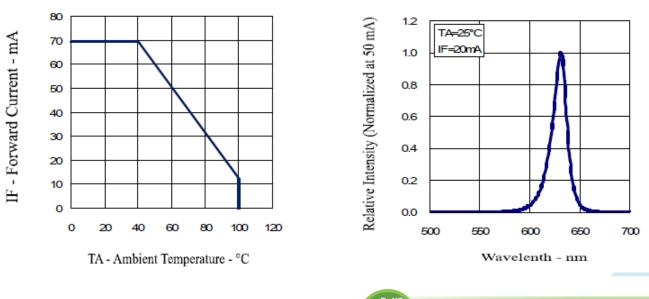


Relative Intensity vs. Forward Current



Forward Current vs. Ambient Temperature

Relative Intensity vs. Wavelength

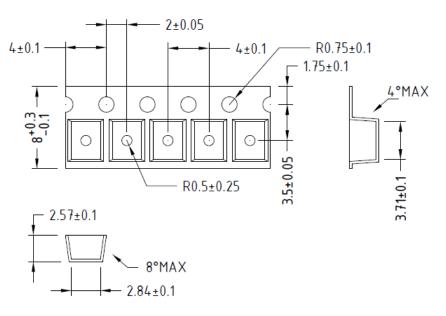




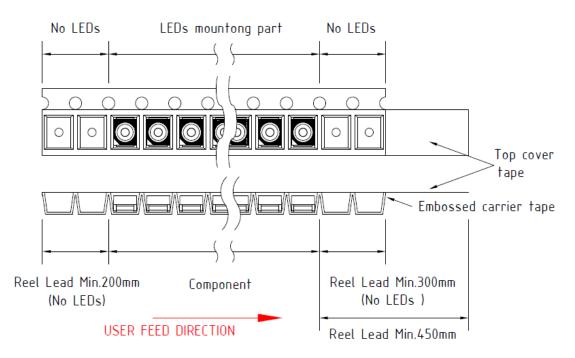


PACKAGING SPECIFICATION

TAPE DIMENSION



TAPE LEADER AND TRAILER DIMENSION



Notes:

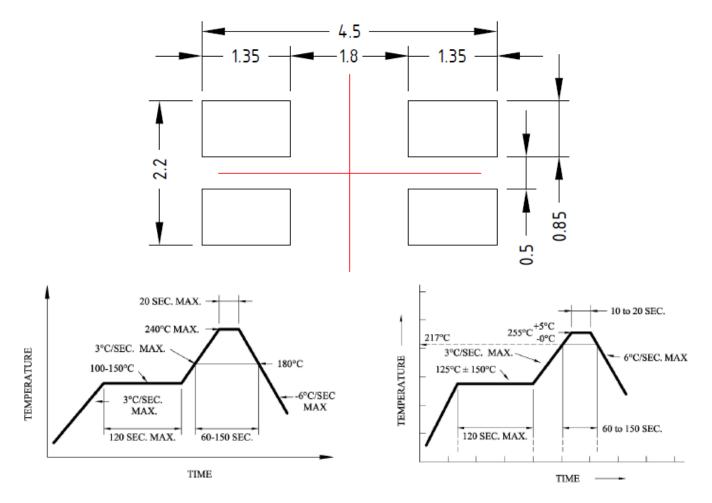
- 1. Empty component pockets are sealed with top cover tape
- 2. The maximum number of missing lamps is two.
- 3. 2000 pcs/reel



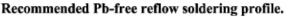


SOLDERING CONDITIONS

RECOMMENDED SOLDERING PAD PATTERN







- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board

